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أحجزن	,	.,	•

	· · · · · ·			
-	. 6		USPAT;	2003/08/10
1		near (holder stage platform platen	US-PGPUB	20:38
1		wafer))) and (((359/509).CCLS.)		
		((250/431,428).CCLS.) ((356/36).CCLS.)	Ì	
		((156/345.12,345.13,345.15).CCLS.))		
	23	((150/545.12,545.15).CCLS.))	1	
-	23		USPAT;	2003/08/10
	,	near (holder stage platform platen	US-PGPUB	20:42
		wafer))) and (lens same (housing		
		chamber))		
-	23	1	IICDAM.	2002 (00 (10
		noar /holder store platform whater	USPAT;	2003/08/10
		near (holder stage platform platen	US-PGPUB	20:42
	Ì	wafer))) and (lens same (housing		
		chamber))) not (((cvp cmp polish\$3		
		etch\$3) and (dummy near (holder stage		
		platform platen wafer))) and		
	.	(((359/509).CCLS.) ((250/431,428).CCLS.)		_
		((356/36).CCLS.)	<i>'</i>	
1_	E007	((156/345.12,345.13,345.15).CCLS.)))		
-	5807	((cvp cmp polish\$ etch\$) and (lens same	USPAT;	2003/08/10
		(housing chamber)))	US-PGPUB	20:51
-	672	(((cvp cmp polish\$ etch\$) and (lens same	USPAT;	2003/08/10
		(housing chamber)))) and ((first	US-PGPUB	20:52
1		second\$3 primary another other two) near	33 13100	20.02
1		(plater platform store surrent two) near		
		(platen platform stage support chuck))		
- \	1	(((359/509).CCLS.) ((250/431,428).CCLS.)	USPAT;	2003/08/10
		((356/36).CCLS.)	US-PGPUB	20:53
1		((156/345.12,345.13,345.15).CCLS.)) and		1
i i		((((cvp cmp polish\$ etch\$) and (lens same		1.
		(housing chamber)))) and ((first		
		second\$3 primary another other two) near		· .
		(alata alata another other two) near	1	1
ļ	0.40	(platen platform stage support chuck)))		1
_	242	The first	USPAT;	2003/08/10
	1	(housing chamber)))) and ((first	US-PGPUB	20:53
	ľ	second\$3 primary another other two) near		
1		(platen platform stage support chuck)))		
1_	1.00	and (nitrogen inert)		/
-	160	((((cvp cmp polish\$ etch\$) and (lens	USPAT;	2003/08/10
		same (housing chamber)))) and ((first	US-PGPUB	20:53
		second\$3 primary another other two) near		
	1	(platen platform stage support chuck)))		
		and (nitrogen inert)) and (extract)		
ŀ	1 .	exhaust)		<u>'</u>
_	56		TICD3m	2002/00/12
	36	(((((cvp cmp polish\$ etch\$) and (lens	USPAT;	2003/08/10 '
		same (housing chamber)))) and ((first	US-PGPUB	20:55
	1 .	second\$3 primary another other two) near		
	ŀ	(platen platform stage support chuck)))		-
	, ,	and (nitrogen inert)) and (extract\$		· .
1		exhaust)) and nozzle	<u> </u>	
-	51	((((((cvp cmp polish\$ etch\$) and (lens	HCDAM.	2002/00/10
	1 71	same (housing chamber))) and (tens	USPAT;	2003/08/10
1		same (housing chamber)))) and ((first	US-PGPUB	20:55
Į.		second\$3 primary another other two) near		.
		(platen platform stage support chuck)))		1
		and (nitrogen inert)) and (extract\$		l l
1.		exhaust)) and nozzle) and valve		
1 -	46	5669979.URPN.	USPAT	2004/05/12
	"	000012.01/L14.	USPAI	
<u> -</u>	1 7/	EE71266 HDDV		16:10
]	76	5571366.URPN.	USPAT	2004/05/12
				16:14
-	222	(wafer same (dummy reference gold\$2)) and	USPAT	2004/05/12
1	'	(lens and nozzle)		16:17
-	16	((wafer same (dummy reference gold\$2))	USPAT	2004/05/12
		and (lens and nozzle)) and ((other	22171	
	ŀ			16:20
]	another differ\$ two second\$3) near		
		nozzle)		
-	16		USPAT	2004/05/12
		and (lens and nozzle)) and ((other		16:36
ľ		another differ\$ two second\$3 dual) near	•	-3.50
	1	nozzle)		
1 -	564		*****	1
	1 204	wafer and ((other another differ\$ two	USPAT	2004/05/12
1		second\$3 dual) near nozzle)		16:24

-	171	(wafer and ((other another differ\$ two	USPAT	2004/05/12
ŀ		second\$3 dual) near nozzle)) and exhaust\$		16:21
-	14	((wafer and ((other another differ\$ two	USPAT	2004/05/12
		second\$3 dual) near nozzle)) and		16:21
		exhaust\$) and lens		
-	87	(wafer and ((other another differ\$ two	USPAT	2004/05/12
		second\$3 dual) near nozzle)) and cmp		16:31
-	60	("3649509" "3727620" "3770598"	USPAT	2004/05/12
		"4027686" "4092176" "4110176"		16:25
1		"4113492" "4315059" "4326940"		·
-	· ·	"4336114" "4376685" "4405416"		
		"4428815" "4435266" "4489740"		
		"4510176" "4518678" "4519846"		
li di	-	"4529353" "4693805" "4732785"		
		"4789445" "4981715" "5039381"		
		"5055425" "5092975" "5100502"		
		"5155336" "5162260" "5222310"		
		"5224504" "5230743" "5252807"		·
		"5256274" "5259407" "5290361"		
		"5316974" "5328589" "5344491"		
		"5349978" "5368711" "5377708"	,	
		"5382885" "5415890" "5429733"		
		"5447615" "5516412" "5608943"		
		"5625170" "5651865" "5705223"		·
1		"5718813" "5723028" "5811951"		j
		"5975834" "6071388" "6093291"		
		"6136163" "6254760" "6258220").PN.		
_	1903	array near nozzle	USPAT	2004/05/12
				16:31
-	255	(array near nozzle) and wafer	USPAT	2004/05/12
			·	16:31
-	9,7	(array near nozzle) and (wafer same	USPAT	2004/05/12
	250	(clean\$ polish\$))		16:31
-	353	lens and ((other another differ\$ two	USPAT	2004/05/12
į	1.00	second\$3 dual) near nozzle)		16:36
-	169	(lens and ((other another differ\$ two	USPAT	2004/05/12
		second\$3 dual) near nozzle)) and (wafer		16:37
	11	semiconduct\$ substrate)		
-	11	((wafer substrate semiconduct\$) near	USPAT	2004/05/12
1	72	clean\$) and (separate near nozzle) platen near chuck		16:43
	12	pracen hear chuck	USPAT	2004/05/12
_	40	(platen near chuck) same wafer	IICDAM	17:02
	10	(pracen hear chack) same water	USPAT	2004/05/12
_	17	(laser near clean\$) and ((reference	USPAT	2004/05/12
		standard\$ dummy gold\$2) near (wafer	ODEAL	17:17
		semiconduct\$ substrate))		- / - + /
1 -	150	(laser same clean\$) and ((reference	USPAT	2004/05/12
	, =====	standard\$ dummy gold\$2) near (wafer		17:17
		semiconduct\$ substrate))		- ' • • '
-	133	((laser same clean\$) and ((reference	USPAT	2004/05/12
		standard\$ dummy gold\$2) near (wafer		17:22
		semiconduct\$ substrate))) not ((laser		
		near clean\$) and ((reference standard\$		
	ŗ	dummy gold\$2) near (wafer semiconduct\$		
	· ·	substrate)))		
-	12	4512659.URPN.	USPAT	2004/05/12
[]	:			17:20
ļ. -	46	(calibrat\$ near wafer) same (support	USPAT	2004/05/12
	.	holder platen chuck stage)		17:22
-	183	(wafer same (clean\$ process\$3)) and	USPAT;	2004/05/12
		((exhaust vacuum evacuat\$) same venturi)	US-PGPUB	17:42
	46	((wafer same (clean\$ process\$3)) and	USPAT;	2004/05/12
		((exhaust vacuum evacuat\$) same venturi))	US-PGPUB	17:42
	_	and cmp		
-	4	((wafer same (clean\$ process\$3)) and	USPAT;	2004/05/12
	.	((exhaust vacuum evacuat\$) same venturi))	US-PGPUB	17:42
	-	and (laser same clean\$)		a to the

L	Hits	Search Text	DB	Time stamp
Number			55	11me Stamp
127	219	(359/509).CCLS.	USPAT;	2004/05/17
128	461	(356/36).CCLs.	US-PGPUB USPAT;	10:16 2004/05/17
129	454	(156/345.12,345.13,345.15).CCLS.	US-PGPUB USPAT;	10:16 2004/05/17
			US-PGPUB	10:16